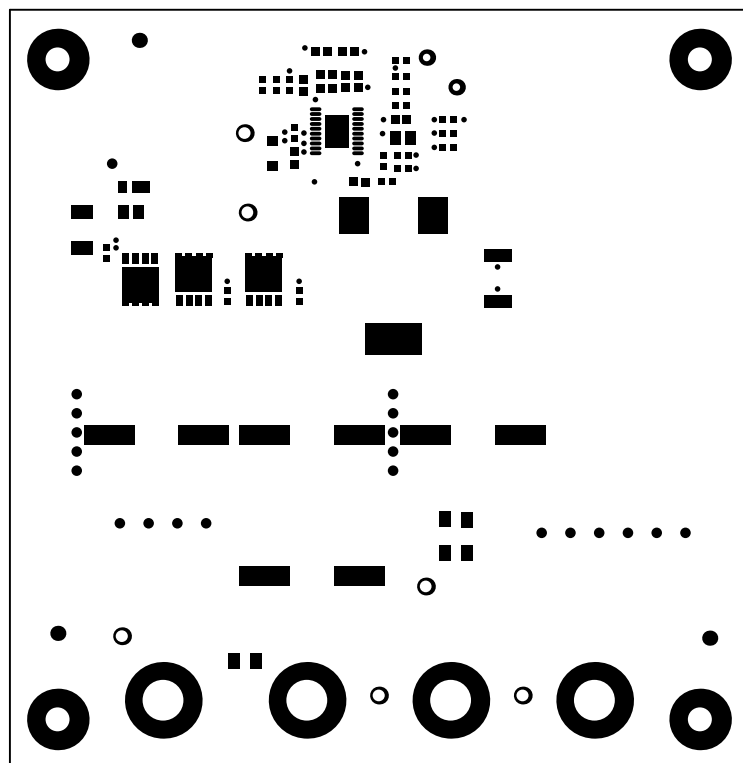
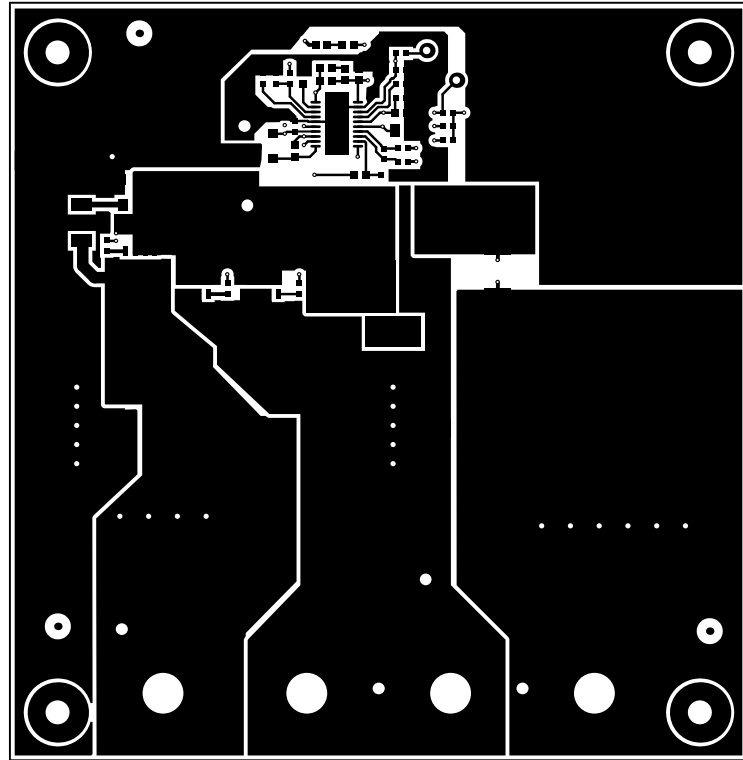


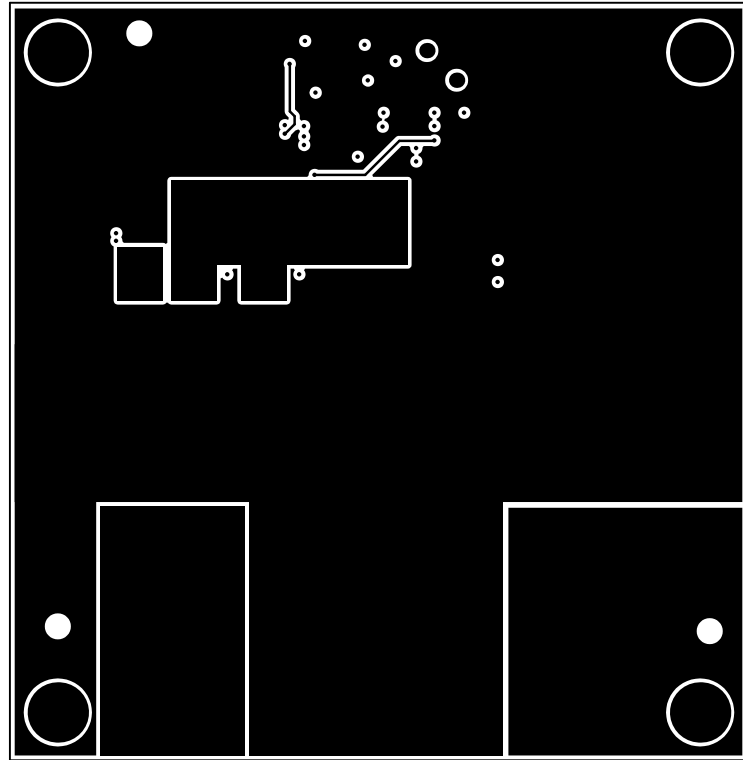
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX7896	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 3/6/2013 8:47:41 AM	TEXAS INSTRUMENTS	



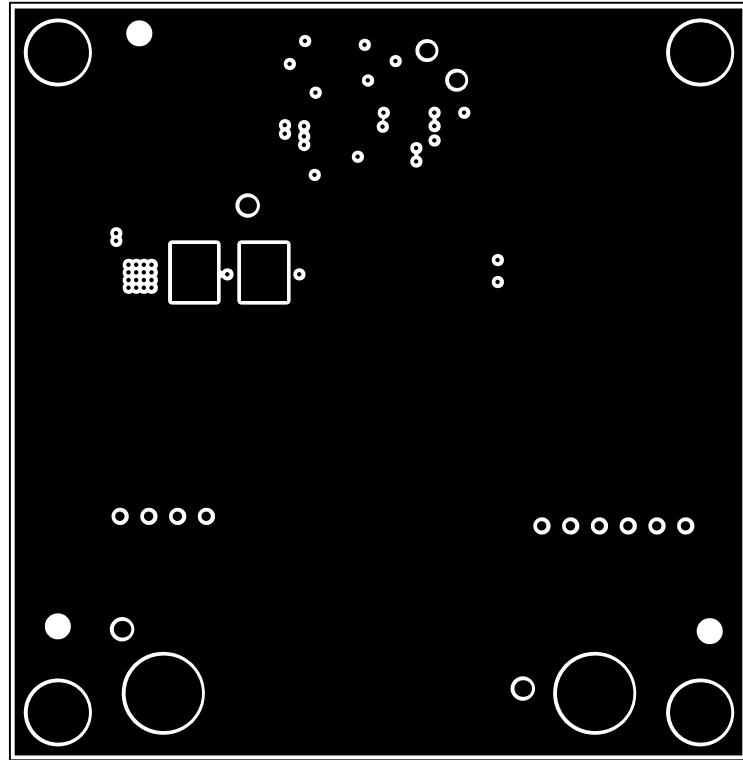
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX7896	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 3/6/2013 8:47:41 AM	TEXAS INSTRUMENTS	



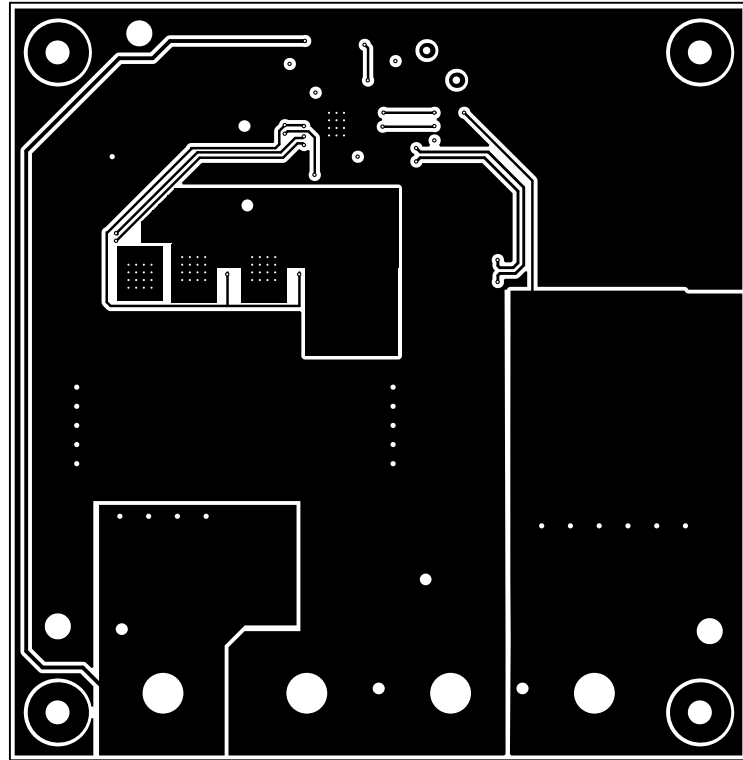
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX7896	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 3/6/2013	8:47:42 AM	TEXAS INSTRUMENTS



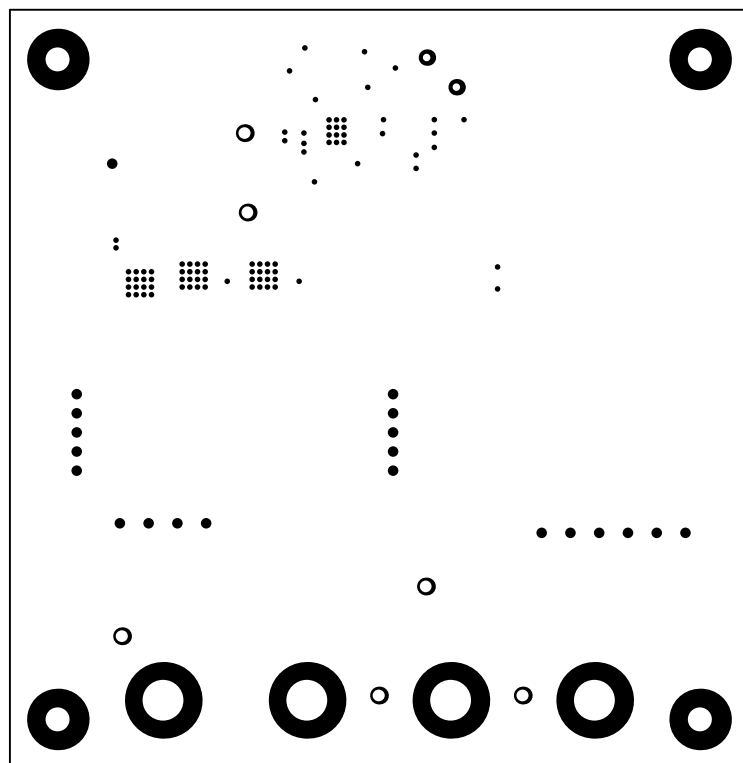
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX7896	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline			
PLOT NAME = Mid Layer 1	GENERATED : 3/6/2013 8:47:42 AM	TEXAS INSTRUMENTS	



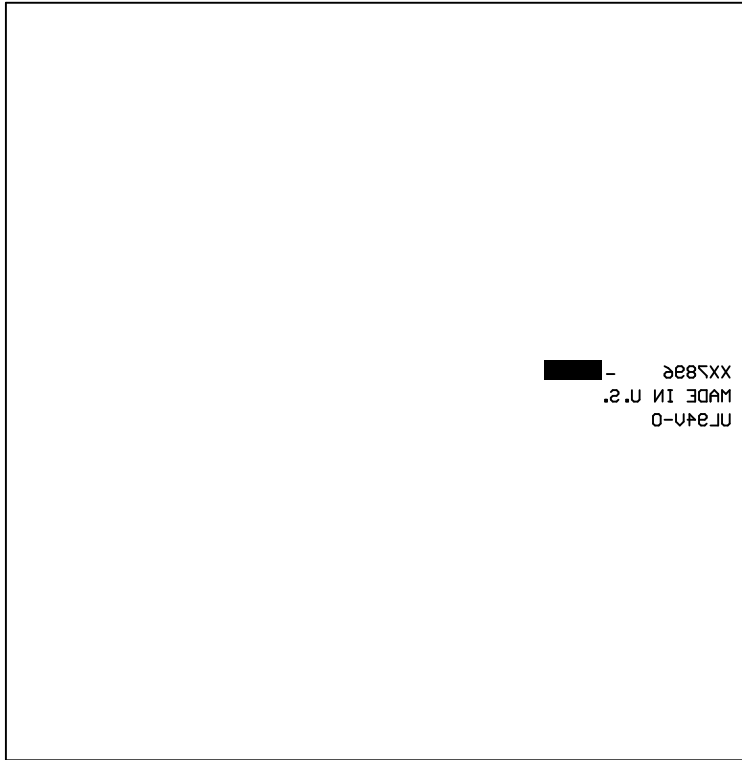
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX7896	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline			
PLOT NAME = Mid Layer 2	GENERATED : 3/6/2013 8:47:43 AM	TEXAS INSTRUMENTS	



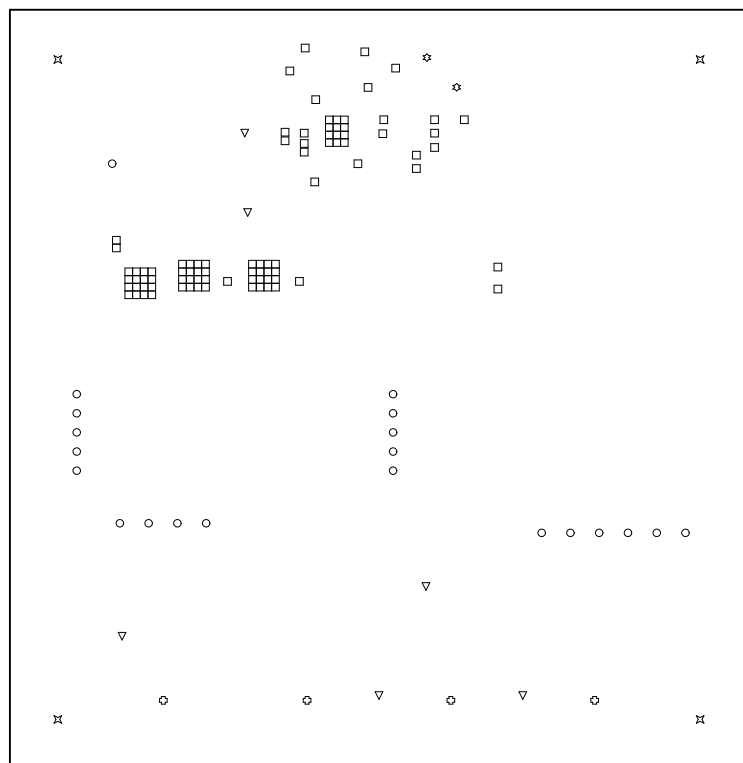
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX7896	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 3/6/2013 8:47:43 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX7896	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 3/6/2013 8:47:44 AM	TEXAS INSTRUMENTS	



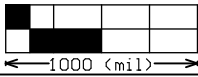
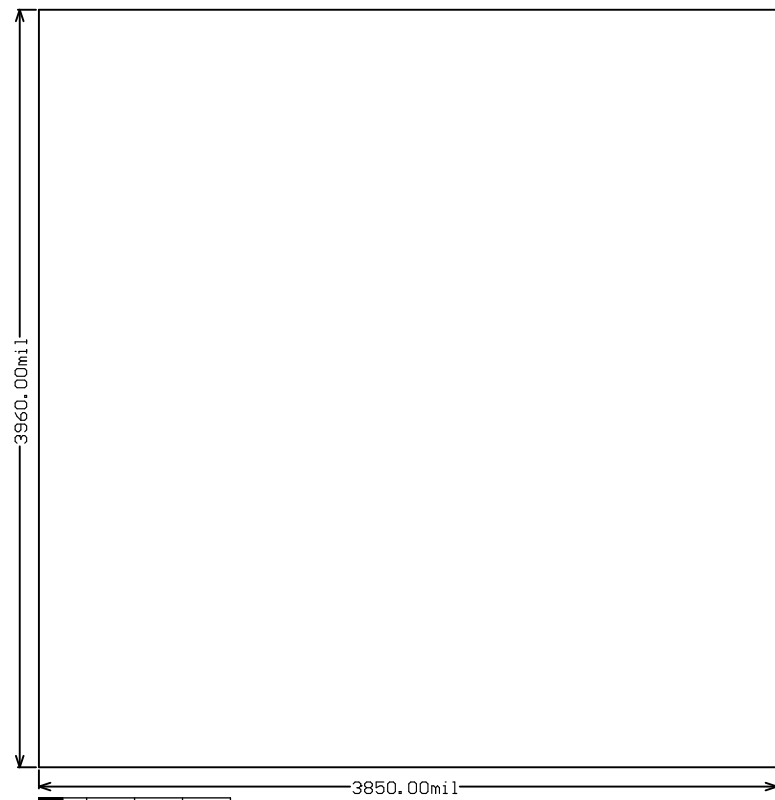
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX7896	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 3/6/2013 8:47:44 AM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
□	87	12mil (0.305mm)	PTH	Round
○	21	28mil (0.711mm)	PTH	Round
☆	2	40mil (1.016mm)	PTH	Round
▽	6	63mil (1.6mm)	PTH	Round
✕	4	125.984mil (3.2mm)	PTH	Round
⊙	4	214.567mil (5.45mm)	PTH	Round
124 Total				

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX7896	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 3/6/2013	8:47:44 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX7896	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 3/6/2013 8:47:45 AM	TEXAS INSTRUMENTS	

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